

Infineon Technologies Key Facts

Headquarters: Munich, Germany

Regional activities: Americas: San Jose, California
Asia Pacific: Singapore
Japan: Tokyo

Fiscal year 2002 revenues:
(ending September 2002) Euro 5.21 billion

Employees (September 2002): About 30,400

Market position in 2002: World's sixth-largest semiconductor manufacturer
(by sales; according to iSupply; status: 03/2003)

Main areas of activity:

- Secure Mobile Solutions
(No. 1 in chip card segment; among the top 3 suppliers for GSM ICs)
- Chips for Wireline Communications
(No. 1 in ISDN, VDSL and 40 Gbit/s optical networking ICs)
- Automotive and Industrial electronics
(No. 2 in automotive segment worldwide; No. 1 in Europe)
- Memory Components
(leading in 300-millimeter technology, No. 3 in DRAM products)

Manufacturing: Eight wafer production sites (frontend fab) including state-of-the-art DRAM manufacturing on three continents (Europe, USA, Asia)

14 sites for assembly and testing (backend)
Research & Development: 27 market and customer-oriented development centers in ten countries

R&D expenditures: about 1 billion Euro
(20 percent of total revenues in fiscal year 2002)

Strategic partnerships:

- UMC
(technology development for building logic chips, joint production in Singapore)
- Toshiba
(technology development)
- AMD and DuPont Photomasks
(joint venture for the development and production of next-generation lithographic photomasks)
- IBM
(technology development, joint manufacturing in France)
- Winbond
(technology licensing and purchasing agreement)
- SMIC
(technology licensing and purchasing agreement)
- Nanya
(technology development and production joint venture in Taiwan)

Ticker symbol: IFX; the company is listed on the DAX index of the Frankfurt Stock Exchange and on the New York Stock Exchange

For further information visit our web site at www.infineon.com